

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSII)

TPC6101

Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance: $RDS(ON) = 48 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 8.2 \text{ S (typ.)}$
- Low leakage current: $IDSS = -10 \mu A (max) (VDS = -20 V)$
- Enhancement-model: V_{th} = -0.5 to -1.2 V (V_{DS} = -10 V, I_D = -200 μA)

Maximum Ratings (Ta = 25°C)

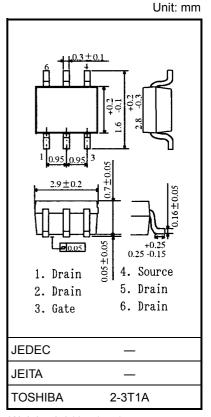
Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-20	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	-20	V	
Gate-source voltage		V _{GSS}	±12	V	
	DC	ID	-4.5	А	
Drain current	(Note 1)	טי	- 4.5		
Diam current	Pulse	I _{DP}	-18		
	(Note 1)	יטף	-10		
Drain power dissipation	(t = 5 s)	PD	2.2	w	
	(Note 2a)	ט י	2.2	VV	
Drain power dissipation	(t = 5 s)	PD	0.7	w	
	(Note 2b)	ט י	0.1	VV	
Single pulse avalanche energy (Note 3)		E _{AS}	3.3	mJ	
Avalanche current	I _{AR}	-2.25	Α		
Repetitive avalanche energy (Note 4)		E _{AR}	0.22	mJ	
Channel temperature	T _{ch}	150	°C		
Storage temperature range		T _{stg}	-55 to 150	°C	

Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient $(t=5\;\text{s}) \tag{Note 2a}$	R _{th (ch-a)}	56.8	°C/W	
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	178.5	°C/W	

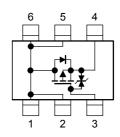
Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) Please see next page.

This transistor is an electrostatically sensitive device. Please handle it with caution.

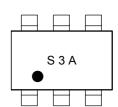


Weight: 0.011 g (typ.)

Circuit Configuration



Marking (Note 5)





Electrical Characteristics (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	ırrent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain-source breakdown voltage		V _{(BR) DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	_	_	V
		V _{(BR) DSX}	$I_D = -10 \text{ mA}, V_{GS} = 12 \text{ V}$	-8	_	_	v
Gate threshold vo	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.5	_	-1.2	V
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = -2 \text{ V}, I_D = -2.2 \text{ A}$	_	110	180	mΩ
		R _{DS} (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -2.2 \text{ A}$	_	75	100	
		R _{DS} (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -2.2 \text{ A}$	_	48	60	
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.2 \text{ A}$	4.1	8.2	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	830	_	pF
Reverse transfer capacitance		C _{rss}		_	300	_	
Output capacitance		C _{oss}		_	370		
Switching time	Rise time	t _r	V _{GS} 0 V 1 _D = -2.2 A	_	6	_	
	Turn-ON time	t _{on}		_	11	_	
	Fall time	t _f		_	57	_	ns
	Turn-OFF time	t _{off}	V _{DD} ≃ −10 V Duty ≦ 1%, t _w = 10 μs	_	112	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -16 \text{ V}, V_{GS} = -5 \text{ V},$ $I_{D} = -4.5 \text{ A}$		12		
Gate-source charge		Q _{gs}		_	6		nC
Gate-drain ("miller") charge		Q _{gd}			6		

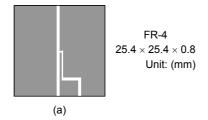
Source-Drain Ratings and Characteristics (Ta = 25°C)

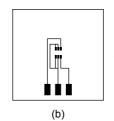
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulse drain reverse current	(Note 1)	I_{DRP}	_	_	_	-18	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)

(b) Device mounted on a glass-epoxy board (b) (t = 5 s)





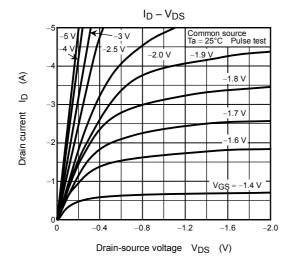
 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{Unit: (mm)} \end{aligned}$

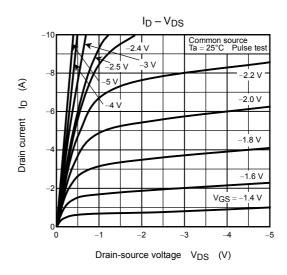
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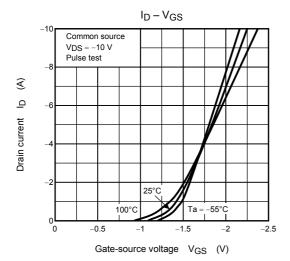
Note 3: $V_{DD}=16~V,~T_{ch}=25^{\circ}C$ (initial), $L=0.5~mH,~R_{G}=25~\Omega,~I_{AR}=-2.25~A$

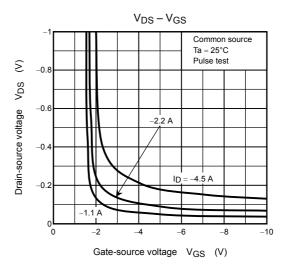
Note 4: Repetitive rating; pulse width limited by maximum channel temperature

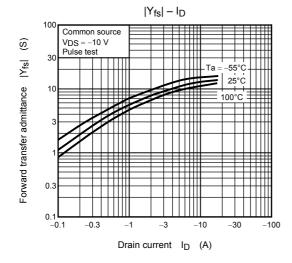
Note 5: Black round marking "•" locates on the left lower side of parts number marking "S3A" indicates terminal No.1.

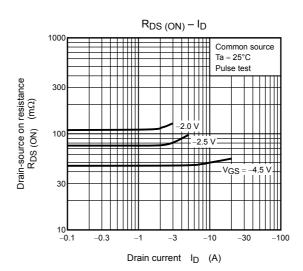




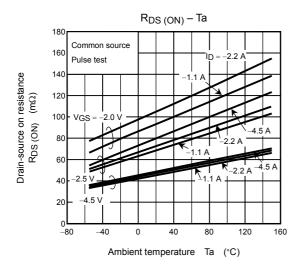


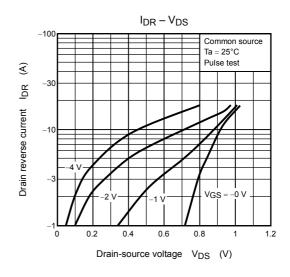


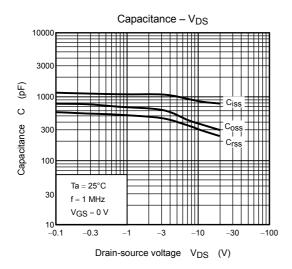


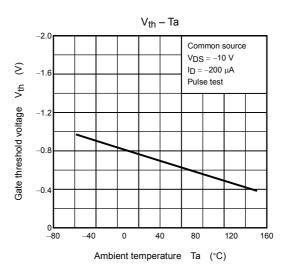


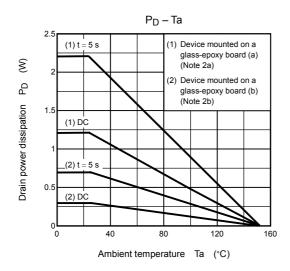
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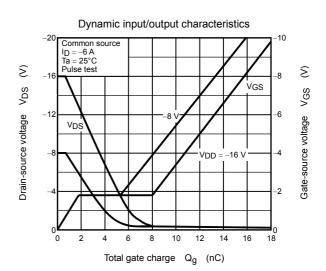




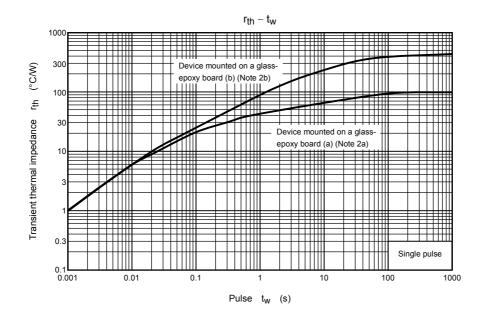


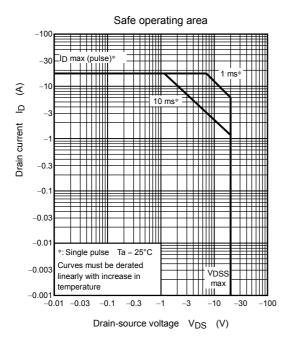






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